



S J P N Trust's

Hirasugar Institute of Technology, Nidasoshi.

Inculcating Values, Promoting Prosperity

Approved by AICTE, Recognized by Govt. of Karnataka and Affiliated to VTU Belagavi.

ECE Dept.


Exam.

Internal Assessment

Even Sem(2017-18)

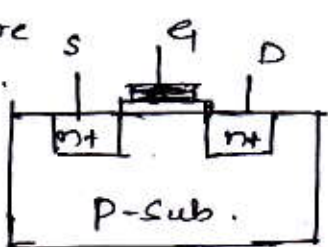
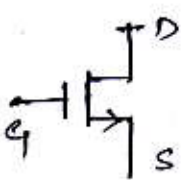
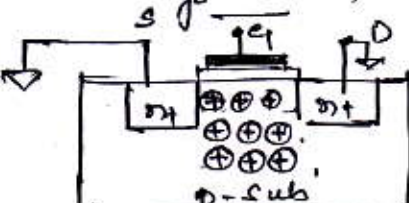
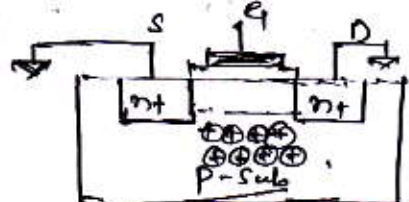
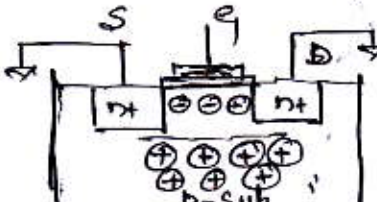
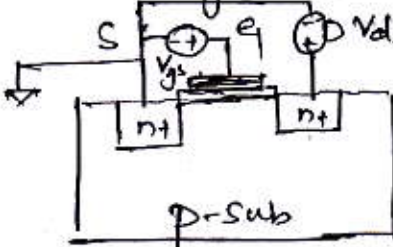
FIRST INTERNAL ASSESSMENTSem : VI
Date:06/03/2018Sub: VLSI DESIGN
Time: 11:00AM-12.00NSub. Code: 15EC63
Max. Marks: 25*Note: Answer two full questions, draw sketches wherever necessary.*

Q. No.	Description of Question	Marks	CO	RBT LEVEL
1.	a. Explain nMOS enhancement mode MOSFET operation for different values of V_{gs} and V_{ds} with relevant equations and necessary graphs.	6	C311.1	L2
	b. Derive an expression for current in n-type enhancement mode transistor in triode and saturation regions.	6	C311.1	L3
OR				
2.	a. Explain the following terms briefly i) Threshold Voltage ii) Body effect	6	C311.1	L2
	b. Find the value of body effect parameter and threshold voltage, when the applied substrate bias is 3V. Given $V_{th0} = 0.4V$, $N_A = 10^{16}/cm^3$, thermal voltage is 26mV, $n_i = 1.5 \times 10^{10}/cm^3$, $t_{ox} = 40nm$, $\epsilon_r(si) = 11.9$, $\epsilon_r(ox) = 3.9$.	6	C311.1	L3
3.	a. Explain CMOS inverter transfer characteristics highlighting the regions of the operation.	8	C311.1	L2
	b. Explain the influence of β_p/β_n on the DC transfer characteristics of an Inverter.	5	C311.1	L3
OR				
4.	a. What is noise margin? explain and obtain noise margin values of typical inverter.	5	C311.1	L2
	b. Briefly explain the steps involved in nMOS fabrication process with neat sketches.	8	C311.1	L2


Course Coordinator
Module Coordinator
HOD



SCHEME OF EVALUATION

Sem :	Subject :	Sub Code :	Date :	Marks	CO's	RBT LEVEL
Q. No.	Bit	Description				
1	a.	<p>nMOS enhancement mode MOSFET Structure</p>  <p style="text-align: right;">symbol.</p>  <p>When $V_{gs} < 0$ Accumulation mode. no voltage.</p>  <p style="text-align: right;">$V_{gs} < V_t$ Depletion mode.</p>  <p style="text-align: right;">$V_{gs} > V_t$ Inversion mode</p>  <p>When $V_{gs} < V_t \rightarrow$ cut-off region $\& V_{gs} > V_t \rightarrow$ operation region.</p>  <p style="text-align: right;">When V_{ds} is small $\& V_{ds} < V_{gs} - V_t$ linear region $i_{ds} = \beta (V_{gs} - V_t - \frac{V_{ds}}{2}) V_{ds}$</p>	1 1 1	03111	L2	



SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL	
		<p>∴ When $V_{gs} > V_t$ & V_{ds} is sufficiently more $V_{ds} > V_{gs} - V_t$ - Saturation region - 1</p> <p>∴ current is</p> $i_{ds} = \frac{\beta}{2} (V_{gs} - V_t)^2$				
1	b.	<p>Current expression.</p> <p>Let the nMOSFET is in linear region</p> <p>The current through the device is</p> $i = \frac{dq}{dt} \Rightarrow \frac{Q}{t}$ <p>$Q = CV$ here $C = C_g$ & $V = V_{gs} - V_t$</p>				

CO3114

L3



SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL	
		$Q = C_{ox}WL \cdot \left\{ V_{gs} - \frac{V_{ds}}{2} - V_t \right\}$ & t - time related to velocity of charges $v = \frac{d}{t} \Rightarrow t = \frac{d}{v}$ here $d = L$ $= \frac{L}{v}$ & $v = \mu E$ & $E = \frac{V_{ds}}{L}$ $\Rightarrow i_{ds} = \frac{Q}{t} = \frac{C_{ox}WL \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right)}{L / \mu V_{ds}}$ $= \mu C_{ox} \frac{W}{L} \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right) V_{ds}$ in triode region.	-1 -1 -1	203111		
2	a.	Threshold Voltage (V_t). The voltage above which channel is formed. $V_{gs} > V_{tn}$. V_{tn} - nMOS threshold voltage. (+)ve. $V_{gs} < V_t$ - cut-off region.	-1			L2
		V_{gs} i/p, as source is grounded. PMOSFET: V_{tp} - threshold voltage (-)ve $V_{gs} < V_t$ for ON or channel formation or V_g or $V_{in} < V_{DD} - V_{tp} $. $V_{in} > V_{DD} - V_{tp} $ i.e. $V_{gs} > V_{tp}$ OFF.	-1 -1	203111		



SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL	
		<p>∴ When $V_{gs} > V_t$ & V_{ds} is sufficiently more $V_{ds} > V_{gs} - V_t$ - Saturation region - 1</p> <p>∴ current is</p> $i_{ds} = \frac{\beta}{2} (V_{gs} - V_t)^2$				
1	b.	<p>Current expression.</p> <p>Let the MOSFET is in linear region</p> <p>The current through the device is</p> $i = \frac{dq}{dt} \Rightarrow \frac{Q}{t}$ $Q = CV \text{ here } C = C_g \text{ \& } V = V_{gs} - V_t$		CO3114		L-3

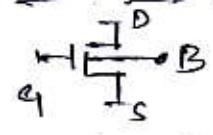



SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL	
		$Q = C_{ox}WL \cdot \left\{ V_{gs} - \frac{V_{ds}}{2} - V_t \right\}$ & t - time related to velocity of charges $v = \frac{d}{t} \Rightarrow t = \frac{d}{v}$ here $d = L$ $= \frac{L}{v}$ & $v = \mu E$ & $E = \frac{V_{ds}}{L}$ $\Rightarrow i_{ds} = \frac{Q}{t} = \frac{C_{ox}WL \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right)}{L / \mu V_{ds}}$ $= \mu C_{ox} \frac{W}{L} \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right) V_{ds}$ in triode region. $i_{ds} = \beta \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right) V_{ds}$ & when $V_{ds} = V_{gs} - V_t \rightarrow$ we get saturation region current $i_{ds} = \beta / 2 (V_{gs} - V_t)^2$	1 1 1	203114		
2	a.	<p>Threshold Voltage (V_t). The voltage above which channel is formed. $V_{gs} > V_{tn}$. V_{tn} - nMOS threshold voltage. (+)ve. $V_{gs} < V_t$ - cut-off region. V_{gs} i/p, as source is grounded. PMOSFET: V_{tp} - threshold voltage (-)ve. $V_{gs} < V_t$ for ON or channel formation or V_g or $V_{in} < V_{DD} - V_{tp}$. $V_{in} > V_{DD} - V_{tp}$ i.e. $V_{gs} > V_{tp}$ OFF.</p>	1 1 1	203114		L2



SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description		Marks	CO's	RBT LEVEL
2.	b	<p><u>Body Effect</u>: The potential difference between the body & Source V_{sb} affects threshold voltage</p>  $V_t = V_{t0} + \gamma \left\{ \sqrt{\phi_s + V_{sb}} - \sqrt{\phi_s} \right\}$ <p>ϕ_s - surface potential γ - body effect parameter (0.4 to 1 $V^{1/2}$) N_A → doping level</p> $\phi_s = 2V_T \ln \frac{N_A}{n_i}$ $\gamma = \frac{t_{ox}}{E_{ox}} \sqrt{2q \epsilon_{si} N_A}$		4		
2	b	<p>$\gamma = ?$ $V_t = ?$</p> <p>$V_b = 3V, V_{t0} = 0.4V, N_A = 10^{18}/cm^3$ $n_T = 0.026, n_i = 1.5 \times 10^{10}/cm^3$ $t_{ox} = 40nm, \epsilon_r = 11.9$ $E_{ox} = 3.9$</p>  $\gamma = \frac{\sqrt{2q \epsilon_{si} N_A}}{C_{ox}} \quad \left\{ C_{ox} = \frac{t_{ox}}{E_{ox}} \right\}$ $= \frac{40 \times 10^{-7} \sqrt{2 \times 1.6 \times 10^{-19} \times 11.9 \times 8.854 \times 10^{-14}}}{3.9 \times 8.854 \times 10^{-10}}$ $= 0.672$ $V_t = V_{t0} + \gamma \left(\sqrt{\phi_s + V_{sb}} - \sqrt{\phi_s} \right)$ $\phi_s = 2V_T \ln \frac{N_A}{n_i} = 2 \times 0.026 \ln \frac{10^{18}}{1.5 \times 10^{10}}$ $= 0.936$ $V_t = 0.4 + 0.672 \left(\sqrt{0.936 + 3} - \sqrt{0.936} \right)$ $= 0.4 + 0.459 = 0.859V$	L3	2		

CO311.1

CO311.1



SCHEME OF EVALUATION

Sem :	Subject :	Sub Code :	Date :
Q. No.	Bit	Description	Marks
			CO's
			RBT LEVEL
10.	a.	<p>CMOS inverter transfer characteristics.</p> <p>cut-off linear Saturation:</p> <p>nMOS. $V_{gs} < V_{tn}$ $V_{gs} > V_t$ $V_{gs} > V_t$ $V_{ds} < V_{gs} - V_t$ $V_{ds} > V_{gs} - V_t$</p> <p>pMOS. $V_{gs} > V_t$ $V_{gs} < V_t$ $V_{gs} < V_t$ $V_{ds} > V_{gs} - V_t$ $V_{ds} < V_{gs} - V_t$</p> <p>i/p o/p. Region nMOS pMOS. -2</p> <p>$V_{in} \approx 0 < V_{tn}$ $\approx V_{DD}$ A cut-off linear</p> <p>$V_{tn} < V_{in} < \frac{V_{DD}}{2}$ $> \frac{V_{DD}}{2}$ B Saturation linear</p> <p>$\frac{V_{DD}}{2}$ $\frac{V_{DD}}{2}$ C Saturation Saturation</p> <p>$\frac{V_{DD}}{2} < V_{in} < V_{DD} - V_{tp}$ $< \frac{V_{DD}}{2}$ D linear Saturation</p> <p>$V_{in} > V_{DD} - V_{tp}$ ≈ 0 E linear cut off -2</p> <p>explanation — ①.</p>	20311.1
3.	b.		



SCHEME OF EVALUATION

Sem :	Subject :	Sub Code :	Date :
Q. No.	Bit	Description	Marks
3.	b.	<p>β_p/β_n ratio</p> <p>$\beta_p = \mu_p C_{ox} \left(\frac{W}{L}\right)_p$, $\beta_n = \mu_n C_{ox} \left(\frac{W}{L}\right)_n$</p> <p>$\beta_p = \beta_n \Rightarrow \left(\frac{W}{L}\right)_p = \frac{\mu_n}{\mu_p} \left(\frac{W}{L}\right)_n$</p>	<p>3</p> <p>2</p>
A.	a.	<p><u>Noise Margins</u>!</p> <p>$NM_H = V_{OH} - V_{IH}$, $NM_L = V_{IL} - V_{OL}$</p> <p>explanations & values of typical inverter -</p> <p>$NM_H = NM_L \approx \frac{V_{DD}}{2}$</p>	<p>1</p> <p>1+1</p> <p>2</p>

CO311.1 L3

L2

CO311.1



S J P N Trust's

Hirasugar Institute of Technology, Nidasoshi.

Inculcating Values, Promoting Prosperity

Approved by AICTE, Recognized by Govt. of Karnataka and Affiliated to VTU Belagavi.

ECE Dept.

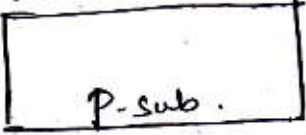
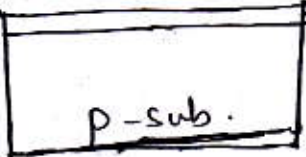
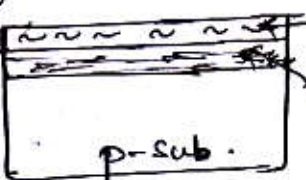
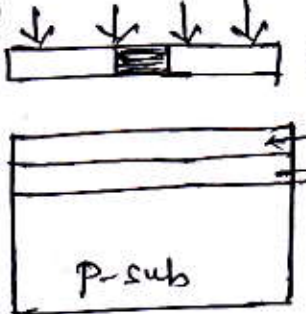
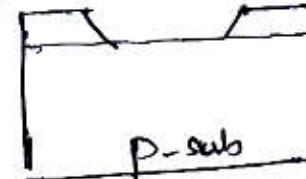
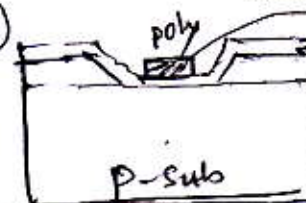
Exam.

IA Scheme Evaluation

Even Sem (2017-18)

Page No. 7 / 08

SCHEME OF EVALUATION

Sem :	Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL
4.	b.	<p>nMOS fabrication Process.</p> <p>①.  75-150mm, 0.4-0.5mm thick $10^{15} - 10^{16} / \text{cm}^3$ $R \rightarrow 2 - 25 \Omega / \text{cm}$ → 1</p> <p>②.  1µm SiO₂ oxide layer → 1</p> <p>③.  photoresistive layer oxide layer → 1</p> <p>④.  Mask-1 photoresistive layer SiO₂ → 1</p> <p>⑤.  window in oxide → 1</p> <p>⑥.  poly 1-2 µm (1000Å - 10000Å) thin oxide. by CVD oxide & poly pattern → 1</p>		CO311.1	L2

Staff-In-Charge

Module Coordinator

HOD



S J P N Trust's

Hirasugar Institute of Technology, Nidasoshi.

Inculcating Values, Promoting Prosperity

Approved by AICTE, Recognized by Govt. of Karnataka and Affiliated to VTU Belagavi.

ECE Dept.

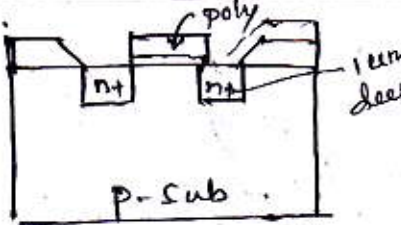
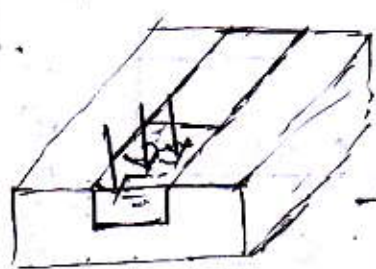
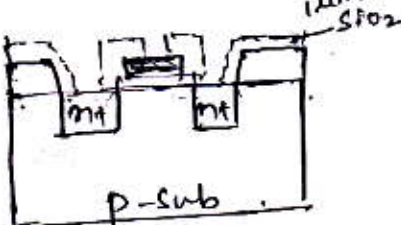
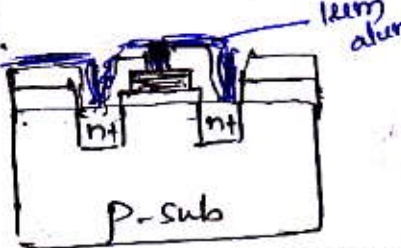
Exam.

IA Scheme Evaluation

Even Sem (2017-18)

Page No. 08 / 08

SCHEME OF EVALUATION

Sem :		Subject :	Sub Code :	Date :		
Q. No.	Bit	Description	Marks	CO's	RBT LEVEL	
4	b	<p>⑦</p>  <p>1µm deep</p> <p>p-sub</p> <p>n+ diffusion</p>  <p>heating & passing phosphorus ions</p> <p>⑧</p>  <p>1µm SiO₂</p> <p>p-sub</p> <p>Contact holes</p> <p>⑨</p>  <p>1µm aluminum</p> <p>p-sub</p> <p>patterned metalization</p> <p>with explanatory stepwise.</p>	1	CO311.1	42	

Staff-In-Charge

Module Coordinator

HOD